

SN74LV4052A-EP

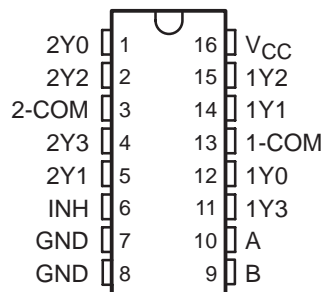
DUAL 4-CHANNEL ANALOG MULTIPLEXER/DEMUTIPLEXER

SCLS502C – MAY 2003 – REVISED MAY 2004

- **Controlled Baseline**
 - One Assembly/Test Site, One Fabrication Site
- **Extended Temperature Performance of –40°C to 105°C**
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product-Change Notification**
- **Qualification Pedigree†**
- **Supports Mixed-Mode Voltage Operation on All Ports**
- **Fast Switching**
- **High On-Off Output-Voltage Ratio**
- **Low Crosstalk Between Switches**
- **Extremely Low Input Current**
- **ESD Protection Exceeds JESD 22**
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

D OR PW PACKAGE
(TOP VIEW)



description/ordering information

This dual 4-channel CMOS analog multiplexer/demultiplexer is designed for 2-V to 5.5-V V_{CC} operation.

The SN74LV4052A handles both analog and digital signals. Each channel permits signals with amplitudes up to 5.5 V (peak) to be transmitted in either direction.

Applications include signal gating, chopping, modulation or demodulation (modem), and signal multiplexing for analog-to-digital and digital-to-analog conversion systems.

ORDERING INFORMATION

T _A	PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 105°C	SOIC – D	Tape and reel	SN74LV4052ATDREP	LV4052ATEP
	TSSOP – PW	Tape and reel	SN74LV4052ATPWREP	L4052EP

‡ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

INPUTS			ON CHANNEL
INH	B	A	
L	L	L	1Y0, 2Y0
L	L	H	1Y1, 2Y1
L	H	L	1Y2, 2Y2
L	H	H	1Y3, 2Y3
H	X	X	None



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



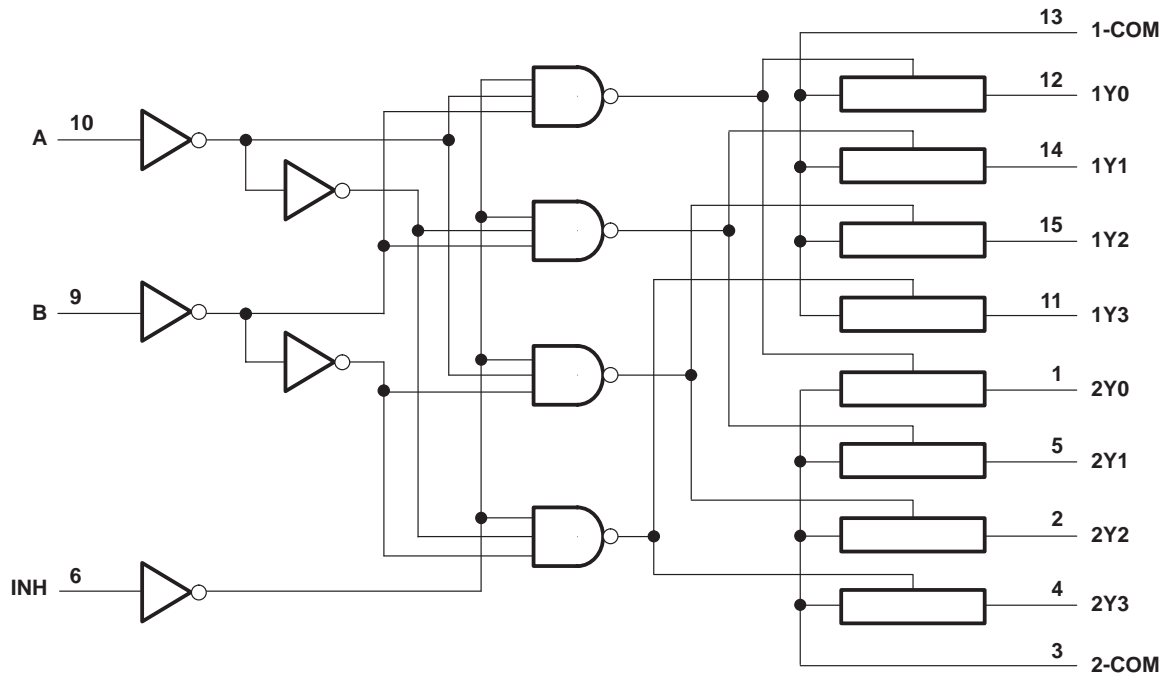
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SN74LV4052A-EP DUAL 4-CHANNEL ANALOG MULTIPLEXER/DEMULTIPLEXER

SCLS502C – MAY 2003 – REVISED MAY 2004

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	-0.5 V to 7.0 V
Input voltage range, V_I (see Note 1)	-0.5 V to 7.0 V
Switch I/O voltage range, V_{IO} (see Notes 1 and 2)	-0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$)	-20 mA
I/O diode current, I_{IOK} ($V_{IO} < 0$)	-50 mA
Switch through current, I_T ($V_{IO} = 0$ to V_{CC})	± 25 mA
Continuous current through V_{CC} or GND	± 50 mA
Package thermal impedance, θ_{JA} (see Note 3): D package	73°C/W
..... PW package	108°C/W
Storage temperature range, T_{stg}	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
 2. This value is limited to 5.5 V maximum.
 3. The package thermal impedance is calculated in accordance with JESD 51-7.

SN74LV4052A-EP

DUAL 4-CHANNEL ANALOG MULTIPLEXER/DEMULTIPLEXER

SCLS502C – MAY 2003 – REVISED MAY 2004

recommended operating conditions (see Note 4)

		MIN	MAX	UNIT
V _{CC}	Supply voltage	2 [†]	5.5	V
V _{IH}	High-level input voltage, control inputs	V _{CC} = 2 V	1.5	V
		V _{CC} = 2.3 V to 2.7 V	V _{CC} × 0.7	
		V _{CC} = 3 V to 3.6 V	V _{CC} × 0.7	
		V _{CC} = 4.5 V to 5.5 V	V _{CC} × 0.7	
V _{IL}	Low-level input voltage, control inputs	V _{CC} = 2 V	0.5	V
		V _{CC} = 2.3 V to 2.7 V	V _{CC} × 0.3	
		V _{CC} = 3 V to 3.6 V	V _{CC} × 0.3	
		V _{CC} = 4.5 V to 5.5 V	V _{CC} × 0.3	
V _I	Control input voltage	0	5.5	V
V _{IO}	Input/output voltage	0	V _{CC}	V
Δt/Δv	Input transition rise or fall rate	V _{CC} = 2.3 V to 2.7 V	200	ns/V
		V _{CC} = 3 V to 3.6 V	100	
		V _{CC} = 4.5 V to 5.5 V	20	
T _A	Operating free-air temperature	-40	105	°C

[†] With supply voltages at or near 2 V, the analog switch on-state resistance becomes very nonlinear. It is recommended that only digital signals be transmitted at these low supply voltages.

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	MAX	UNIT
r _{on}	I _T = 2 mA, V _I = V _{CC} or GND, V _{INH} = V _{IL} , (see Figure 1)	2.3 V	225	Ω	
		3 V	190		
		4.5 V	100		
r _{on(p)}	I _T = 2 mA, V _I = V _{CC} to GND, V _{INH} = V _{IL}	2.3 V	600	Ω	
		3 V	225		
		4.5 V	125		
Δr _{on}	I _T = 2 mA, V _I = V _{CC} to GND, V _{INH} = V _{IL}	2.3 V	40	Ω	
		3 V	30		
		4.5 V	20		
I _I	V _I = 5.5 V or GND	0 to 5.5 V		±1	μA
I _{S(off)}	V _I = V _{CC} and V _O = GND, or V _I = GND and V _O = V _{CC} , V _{INH} = V _{IH} , (see Figure 2)	5.5 V		±1	μA
I _{S(on)}	V _I = V _{CC} or GND, V _{INH} = V _{IL} , (see Figure 3)	5.5 V		±1	μA
I _{CC}	V _I = V _{CC} or GND	5.5 V		20	μA



SN74LV4052A-EP

DUAL 4-CHANNEL ANALOG MULTIPLEXER/DEMULTIPLEXER

SCLS502C – MAY 2003 – REVISED MAY 2004

switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ (unless otherwise noted)

PARAMETER		FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	MAX	UNIT
t_{PLH} t_{PHL}	Propagation delay time	COM or Y	Y or COM	$C_L = 50\text{ pF}$, (see Figure 4)		12	ns
t_{PZH} t_{PZL}	Enable delay time	INH	COM or Y	$C_L = 50\text{ pF}$, (see Figure 5)		25	ns
t_{PHZ} t_{PLZ}	Disable delay time	INH	COM or Y	$C_L = 50\text{ pF}$, (see Figure 5)		25	ns

switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted)

PARAMETER		FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	MAX	UNIT
t_{PLH} t_{PHL}	Propagation delay time	COM or Y	Y or COM	$C_L = 50\text{ pF}$, (see Figure 4)		8	ns
t_{PZH} t_{PZL}	Enable delay time	INH	COM or Y	$C_L = 50\text{ pF}$, (see Figure 5)		18	ns
t_{PHZ} t_{PLZ}	Disable delay time	INH	COM or Y	$C_L = 50\text{ pF}$, (see Figure 5)		18	ns

analog switch characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	V_{CC}	$T_A = 25^\circ\text{C}$			UNIT
					MIN	TYP	MAX	
Frequency response (switch on)	COM or Y	Y or COM	$C_L = 50\text{ pF}$, $R_L = 600\ \Omega$, $f_{in} = 1\text{ MHz}$ (sine wave) (see Note 5 and Figure 6)	2.3 V	30		MHz	
				3 V	35			
				4.5 V	50			
Crosstalk (between any switches)	COM or Y	Y or COM	$C_L = 50\text{ pF}$, $R_L = 600\ \Omega$, $f_{in} = 1\text{ MHz}$ (sine wave) (see Note 6 and Figure 7)	2.3 V	-45		dB	
				3 V	-45			
				4.5 V	-45			
Crosstalk (control input to signal output)	INH	COM or Y	$C_L = 50\text{ pF}$, $R_L = 600\ \Omega$, $f_{in} = 1\text{ MHz}$ (square wave) (see Figure 8)	2.3 V	20		mV	
				3 V	35			
				4.5 V	65			
Feedthrough attenuation (switch off)	COM or Y	Y or COM	$C_L = 50\text{ pF}$, $R_L = 600\ \Omega$, $f_{in} = 1\text{ MHz}$ (sine wave) (see Note 6 and Figure 9)	2.3 V	-45		dB	
				3 V	-45			
				4.5 V	-45			
Sine-wave distortion	COM or Y	Y or COM	$C_L = 50\text{ pF}$, $R_L = 10\text{ k}\Omega$, $f_{in} = 1\text{ kHz}$ (sine wave) (see Figure 10)	$V_I = 2\text{ V}_{p-p}$	2.3 V	0.1		%
				$V_I = 2.5\text{ V}_{p-p}$	3 V	0.1		
				$V_I = 4\text{ V}_{p-p}$	4.5 V	0.1		

NOTES: 5. Adjust f_{in} voltage to obtain 0 dBm at output. Increase f_{in} frequency until dB meter reads -3 dB.
 6. Adjust f_{in} voltage to obtain 0 dBm at input.



operating characteristics, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance	$C_L = 50\text{ pF}, f = 10\text{ MHz}$	11.8	pF

PARAMETER MEASUREMENT INFORMATION

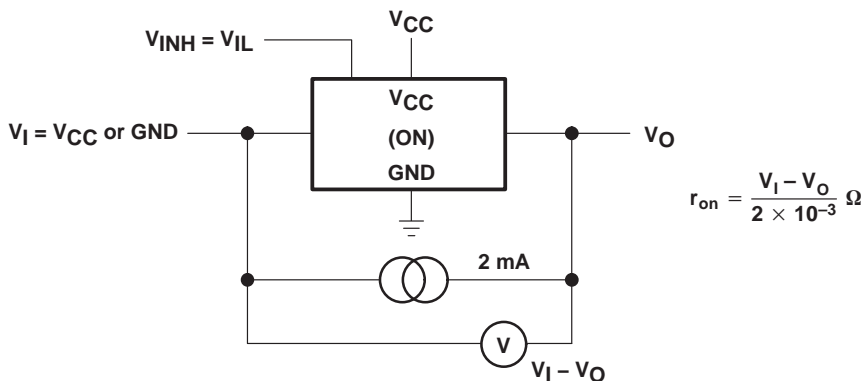


Figure 1. On-State Resistance Test Circuit

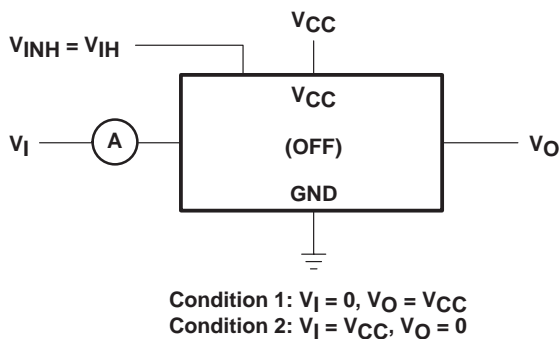


Figure 2. Off-State Switch Leakage-Current Test Circuit

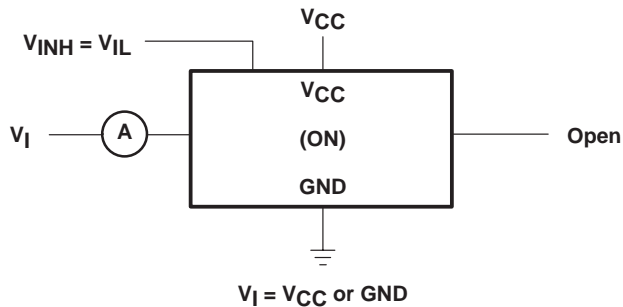


Figure 3. On-State Switch Leakage-Current Test Circuit

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SCLS502C – MAY 2003 – REVISED MAY 2004

PARAMETER MEASUREMENT INFORMATION

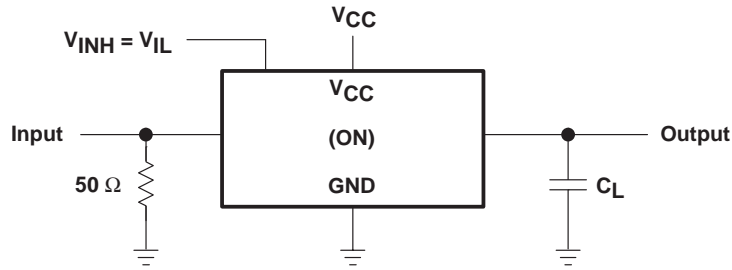
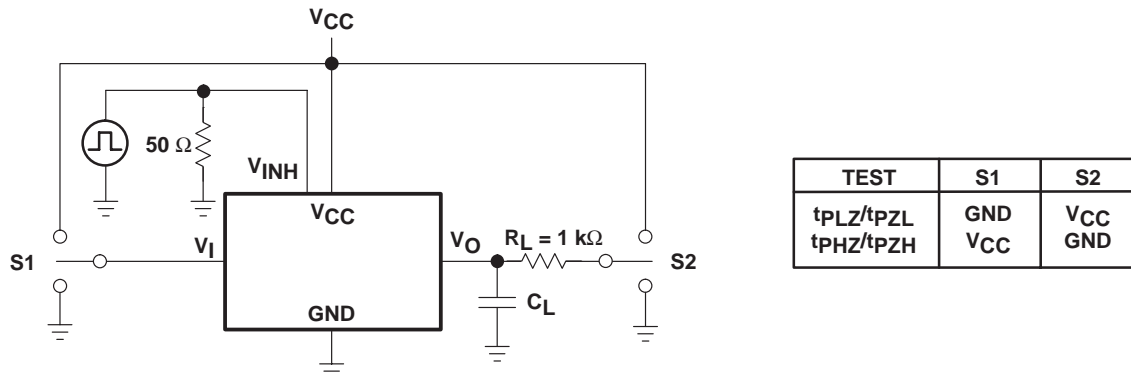


Figure 4. Propagation Delay Time, Signal Input to Signal Output



TEST CIRCUIT

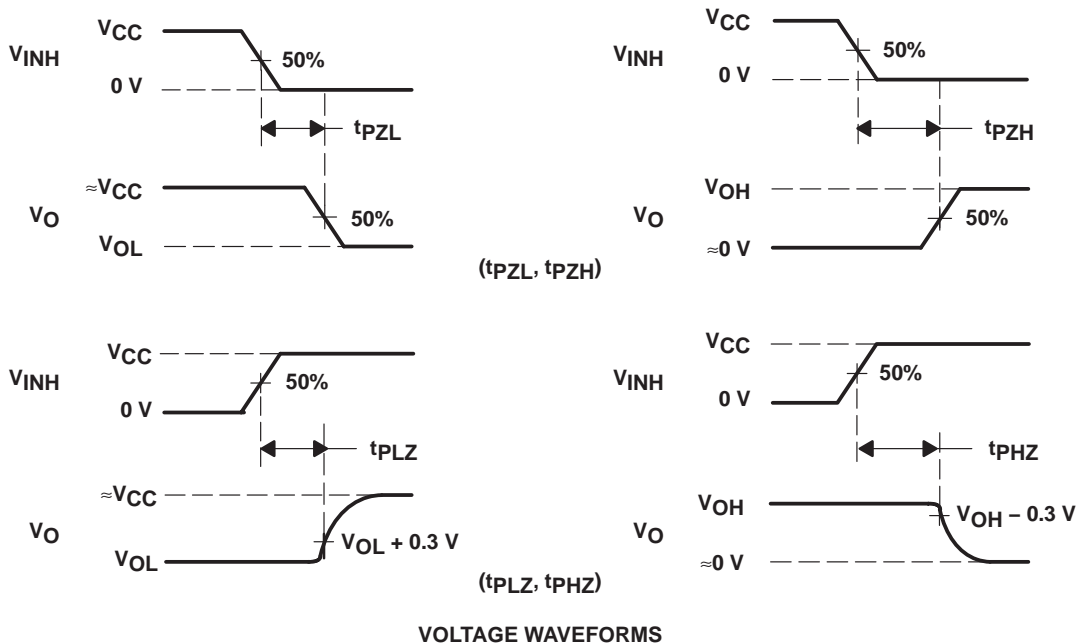
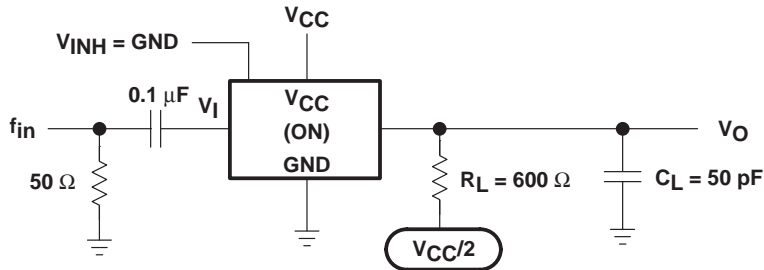


Figure 5. Switching Time (t_{PZL} , t_{PLZ} , t_{PZH} , t_{PHZ}), Control to Signal Output

PARAMETER MEASUREMENT INFORMATION



NOTE A: f_{in} is a sine wave.

Figure 6. Frequency Response (Switch On)

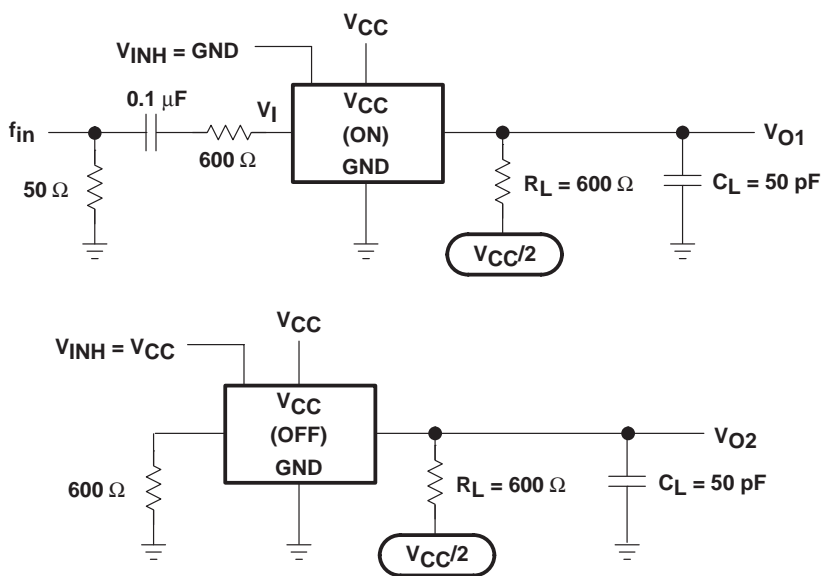


Figure 7. Crosstalk Between Any Two Switches

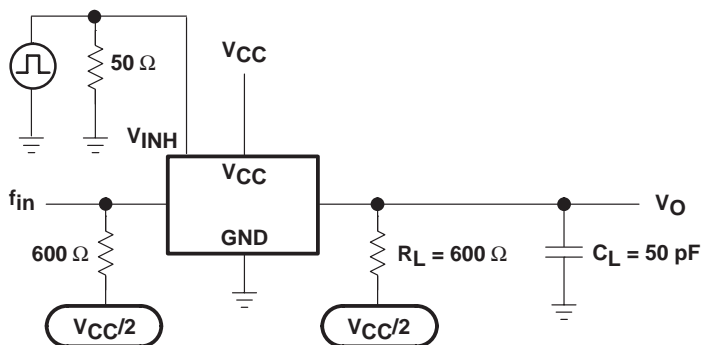


Figure 8. Crosstalk Between Control Input and Switch Output

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SCLS502C – MAY 2003 – REVISED MAY 2004

PARAMETER MEASUREMENT INFORMATION

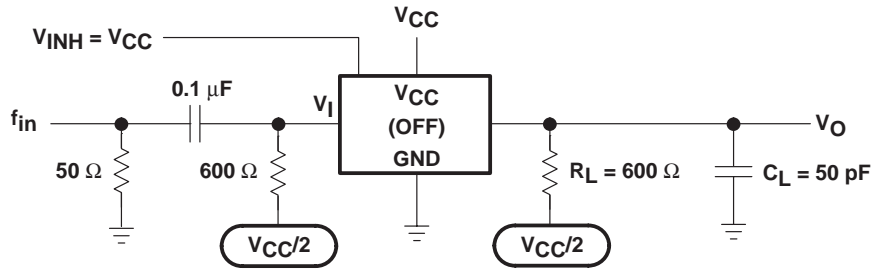


Figure 9. Feedthrough Attenuation (Switch Off)

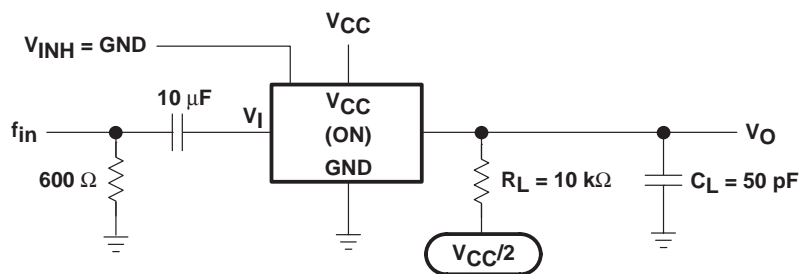


Figure 10. Sine-Wave Distortion

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LV4052ATPWREP	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 105	L4052EP	Samples
V62/03665-01XE	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 105	L4052EP	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN74LV4052A-EP :

- Catalog: [SN74LV4052A](#)
- Automotive: [SN74LV4052A-Q1](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV4052ATPWREP	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV4052ATPWREP	TSSOP	PW	16	2000	367.0	367.0	35.0

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE

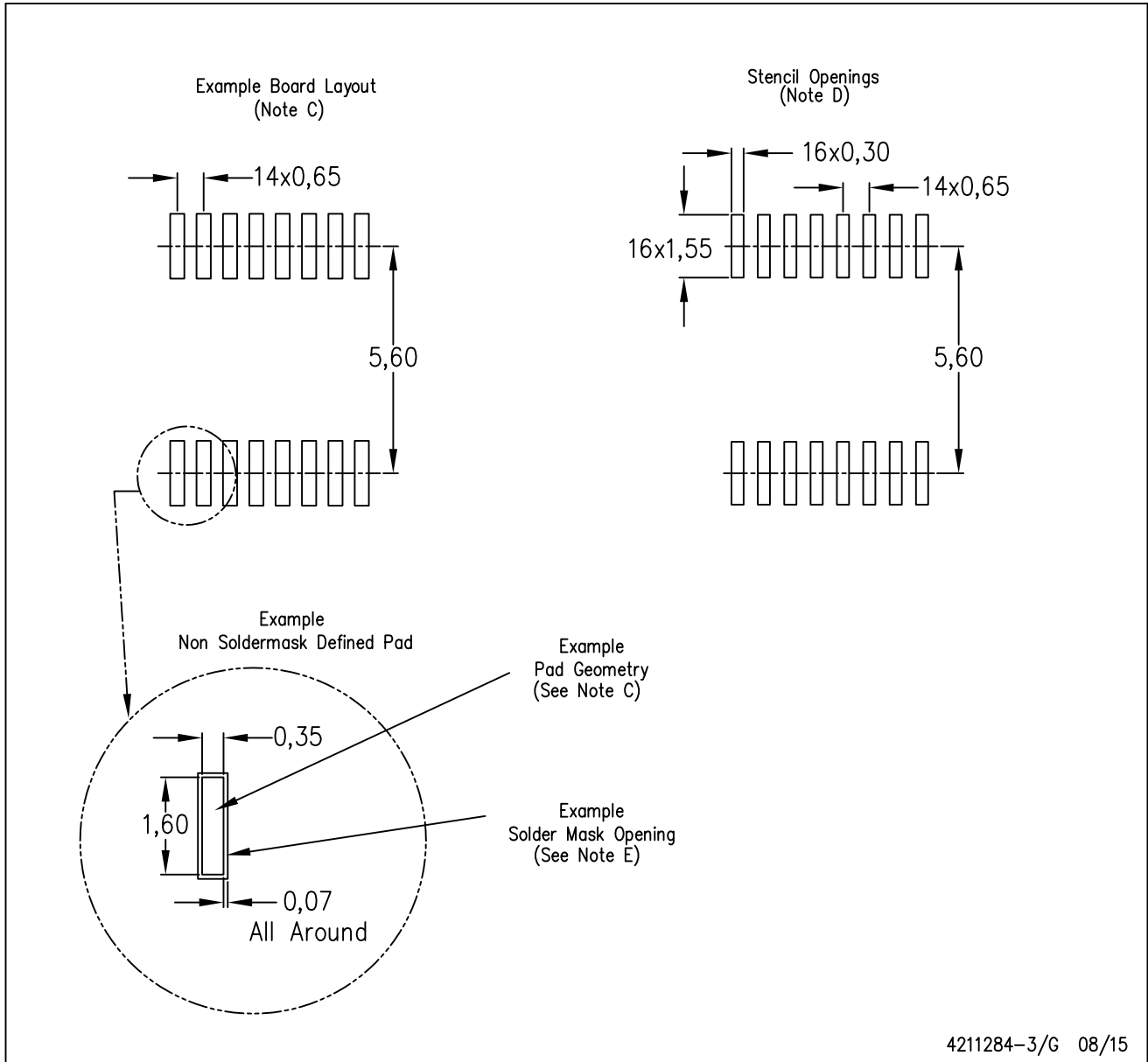


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- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 -  C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 -  D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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